

## **General Description**

The MAX6680/MAX6681 are precise, two-channel digital thermometers. Each accurately measures the temperature of its own die and one remote PN junction and reports the temperature on a 2-wire serial interface. The remote junction can be a diode-connected transistor like the low-cost NPN type 2N3904 or PNP type 2N3906. The remote junction can also be a commoncollector PNP, such as a substrate PNP of a microprocessor.

The MAX6680/MAX6681 include pin-programmable default temperature thresholds for the OVERT output. which provides fail-safe clock throttling or system shutdown. In addition, the devices are pin programmable to select whether the OVERT output responds to either the local, remote, or both temperatures.

The 2-wire serial interface accepts standard System Management Bus (SMBus)™ commands such as Write Byte, Read Byte, Send Byte, and Receive Byte to read the temperature data and program the alarm thresholds and conversion rate. The MAX6680/MAX6681 can function autonomously with a programmable conversion rate, which allows the control of supply current and temperature update rate to match system needs. For conversion rates of 4Hz or less, the remote sensor temperature can be represented in extended mode as 10 bits + sign with a resolution of 0.125°C. When the conversion rate is 8Hz, output data is 7 bits + sign with a resolution of 1°C. The MAX6680/MAX6681 also include an SMBus timeout feature to enhance system reliability.

The MAX6681 is an upgrade to the MAX6654. The MAX6680/MAX6681 remote accuracy is ±1°C with no calibration needed. They are available in a 16-pin QSOP package and operate throughout the -55°C to +125°C temperature range.

## **Applications**

**Desktop Computers** 

Notebook

Computers

Servers

Thin Clients

Workstations

Pin Configurations appear at end of data sheet.

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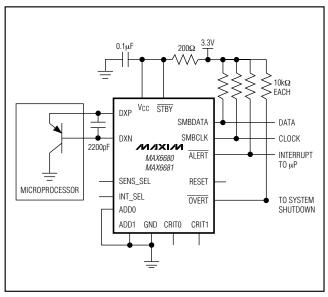
#### **Features**

- **♦ Two Alarm Outputs: ALERT and OVERT**
- ♦ Pin-Programmable Threshold for OVERT Limit
- **♦ Programmable Under/Overtemperature ALERT** Limit
- ◆ Dual Channel: Measures Remote and Local **Temperature**
- ♦ 11-Bit, 0.125°C Resolution for Remote Temperature Measurements
- ♦ High Accuracy ±1°C (max) from +60°C to +100°C (Remote)
- ♦ No Calibration Required
- ♦ SMBus/I<sup>2</sup>C<sup>TM</sup>-Compatible Interface
- ♦ SMBus Timeout Prevents SMBus Lockup

## **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX6680MEE	-55°C to +125°C	16 QSOP
MAX6681MEE	-55°C to +125°C	16 QSOP

## Typical Operating Circuit



MIXIM

Maxim Integrated Products 1

### **ABSOLUTE MAXIMUM RATINGS**

Vcc	
DXP	
DXN	
SMBCLK, SMBDATA, ALERT, OVERT	
RESET, INT_SEL, STBY, ADD0, ADD1	0.3V to +6V
CRIT1, CRIT0, SENS_SEL	
SMBDATA, ALERT, OVERT, Current	1mA to +50mA
DXN Current	±1mA

Continuous Power Dissipation ( $T_A = +70$ °C)	
16-Pin QSOP (derate 8.3mW/°C above +70°C	c)664mW
Junction Temperature	+150°C
Storage Temperature Range	
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

(Circuit of Typical Operating Circuit,  $V_{CC} = 3.0V$  to 5.5V,  $T_A = -25^{\circ}C$  to  $+125^{\circ}C$ , unless otherwise specified. Typical values are at  $V_{CC} = 3.3V$  and  $T_A = +25^{\circ}C$ .)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Temperature Resolution,			1			°C	
Legacy Mode				8		Bits	
Temperature Resolution,			0.125			°C	
Extended Mode				11		Bits	
		$T_{RJ} = +60^{\circ}\text{C to } +100^{\circ}\text{C}, V_{CC} = 3.3\text{V}$	-1.0		+1.0	<u> </u>	
Remote Temperature Error (Note 1)		$T_{RJ} = +50^{\circ}C \text{ to } +120^{\circ}C, V_{CC} = 3.3V$	-2.0		+2.0	°C	
		$T_{RJ} = -55^{\circ}C$ to +125°C, $V_{CC} = 3.3V$	-3.0		+3.0		
		$T_A = +60^{\circ}C \text{ to } +100^{\circ}C, V_{CC} = 3.3V$	-1.5		+1.5		
Local Temperature Error		$T_A = 0^{\circ}C \text{ to } +125^{\circ}C, V_{CC} = 3.3V$	-3.0		+3.0	°C	
		$T_A = -55^{\circ}C \text{ to } +125^{\circ}C, V_{CC} = 3.3V \text{ (Note 2)}$	-5.0		+5.0		
Line Regulation		3.0V ≤ V <sub>CC</sub> ≤ 5.5V		0.2	0.6	m°C/V	
Supply Voltage Range	Vcc		3.0		5.5	V	
Undervoltage Lockout Threshold	UVLO	Falling edge of V <sub>CC</sub> disables ADC	2.60	2.80	2.95	V	
Undervoltage Lockout Hysteresis				90		mV	
Power-On Reset (POR) Threshold		V <sub>CC</sub> , falling edge	1.5	2.0	2.5	V	
POR Threshold Hysteresis				90		mV	
Operation Time		Legacy		62.5			
Conversion Time		Extended		125		ms	
Standby Supply Current		SMBus static		3	10	μΑ	
Operating Current		During conversion		0.55	1.0	mA	
Average Operating Current		0.25 conversions/s		35	70		
(Note 3)		2 conversions/s		120	180	μA	
DXP and DXN Leakage Current		In standby mode			2	μΑ	
Remote-Diode Source Current	l= .	High level	80	100	120		
nemote-piode source outrem	I <sub>RJ</sub>	Low level		10	12	μA	

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## **ELECTRICAL CHARACTERISTICS (continued)**

(Circuit of Typical Operating Circuit,  $V_{CC} = 3.0V$  to 5.5V,  $T_A = -25^{\circ}C$  to  $+125^{\circ}C$ , unless otherwise specified. Typical values are at  $V_{CC} = 3.3V$  and  $T_A = +25^{\circ}C$ .)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
CRITO, CRIT1, ADDO, ADD1, RES	ET, INT_SE	L, SENS_SEL	•			•
Logic Input Low Voltage	VIL				0.8	V
Logic Input High Voltage	VIH		2.4			V
Input Leakage Current	ILEAK		-1		+1	μA
(ALERT, OVERT)						
Output Low Sink Current		V <sub>OL</sub> = 0.4V			1	mA
Output High Leakage Current		V <sub>OH</sub> = 5.5V			1	μΑ
SMBus INTERFACE (SMBCLK, S	MBDATA, S	БТВҮ)				
Logic Input Low Voltage	VIL				0.8	V
Lagic locate ligh Voltage	V	V <sub>CC</sub> = 3.0V	2.2			V
Logic Input High Voltage	VIH	V <sub>CC</sub> = 5.5V	2.4			]
Input Leakage Current	ILEAK	V <sub>IN</sub> = GND or V <sub>CC</sub>			±2	μΑ
Output Low Sink Current	loL	V <sub>OL</sub> = 0.6V			6	mA
Input Capacitance	CIN			5		рF
SMBus-COMPATIBLE TIMING (N	ote 5)					
Serial Clock Frequency (Note 5)	fscl				100	kHz
Bus Free Time Between STOP and START Condition	tBUF		4.7			μs
START Condition Setup Time			4.7			μs
Repeat START Condition Setup Time	tsu:sta	90% to 90%	50			ns
START Condition Hold Time	thd:Sta	10% of SMBDATA to 90% of SMBCLK	4			μs
STOP Condition Setup Time	tsu:sto	90% of SMDCLK to 90% of SMBDATA	4			μs
Clock Low Period	tLOW	10% to 10%		4.7		μs
Clock High Period	thigh	90% to 90%	4			μs
Data Setup Time (Note 6)	thd:dat		250			ns
Receive SCL/SDA Rise Time	t <sub>R</sub>				1	μs
Receive SCL/SDA Fall Time	tF				300	ns
Pulse Width of Spike Suppressed	tsp		0		50	ns
SMBus Timeout (Note 5)		SMBDATA low period for interface reset	25	37	45	ms

**Note 1:**  $T_A = +25^{\circ}C$  to  $+85^{\circ}C$ .

**Note 2:** If both the local and the remote junction are below  $T_A = -20^{\circ}C$ , then  $V_{CC} > 3.15V$ .

Note 3: Conversions done in extended mode. For legacy mode, current is approximately half.

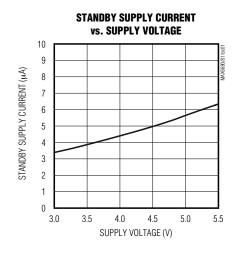
Note 4: Timing specifications guaranteed by design.

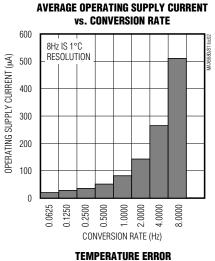
Note 5: The serial interface resets when SMBCLK or SMBDATA is low for more than t<sub>TIMEOUT</sub>.

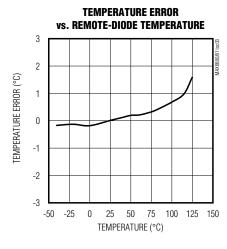
Note 6: A transition must internally provide at least a hold time to bridge the undefined region (300ns max) of SMBCLK's falling edge.

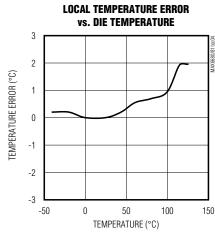
## **Typical Operating Characteristics**

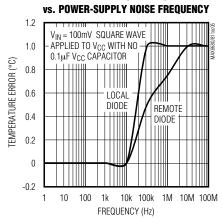
 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

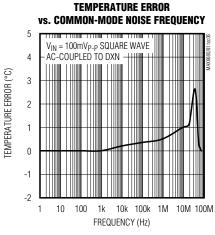


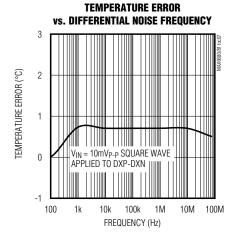


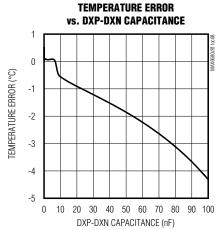












## \_Pin Description

P	PIN					
MAX6680	MAX6681	NAME	FUNCTION			
1	2	Vcc	Supply Voltage Input, 3V to 5.5V. Bypass $V_{CC}$ to GND with a $0.1\mu F$ capacitor. A $200\Omega$ series resistor is recommended, but not required for additional noise filtering. See the <i>Typical Operating Circuit</i> .			
2, 5	1, 5	CRIT1, CRIT0	Hardware-Programmable Default Alarm Threshold for OVERT Limits. Use Table 4 to set default temperatures.			
3	3	DXP	Combined Remote-Diode Current Source and A/D Positive Input for Remote-Diode Channel. DO NOT LEAVE DXP FLOATING; connect DXP to DXN if no remote diode is used. Place a 2200pF capacitor between DXP and DXN for noise filtering.			
4	4	DXN	Combined Remote-Diode Current Sink and A/D Negative Input. DXN is internally biased to one diode drop above ground.			
6	6	ADD1	SMBus Address Select Pin (Table 9). ADD0 and ADD1 are sampled upon power-up. Excess capacitance (>50pF) at the address pins when floating may cause address-recognition problems.			
7	7	RESET	Reset Input. Drive RESET high to set all registers to their default values (POR state). Drive RESET low or leave floating for normal operation.			
8	8	GND	Ground			
9	9	OVERT	Overtemperature Active-Low Output. Open drain.			
10	10	ADD0	SMBus Slave Address Select Pin (see ADD1).			
11	11	ALERT	SMBus Alert (Interrupt) Active-Low Output. Open drain.			
12	12	SMBDATA	SMBus Serial-Data Input/Output, Open Drain			
13	13	INT_SEL	Input. Connect high or leave floating to conform to the standard SMBus ALERT protocol. See the ALERT Interrupts section. Connect to GND to invoke comparator mode, where ALERT is asserted whenever any of the temperature conditions is violated by the remote sensor. In this mode, ALERT can only be deasserted by the condition returning within the temperature limits by enabling the mask bit in the Configuration register.			
14	14	SMBCLK	SMBus Serial-Clock Input			
15	15	STBY	Input. Hardware Standby. Connect to ground to place in device in standby. Supply current drops below 10µA and all registers' data are maintained.			
16	16	SENS_SEL	Input. Selects which temperature sensor (local, remote, or both) activates OVERT.			
			High = Remote, Low = Local, Open = Local and Remote			

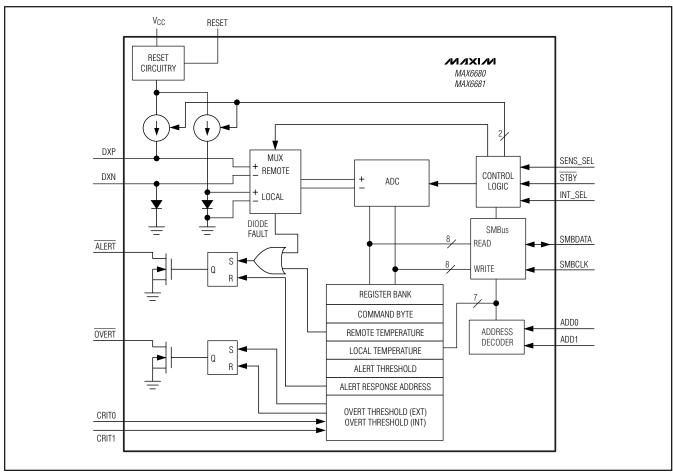


Figure 1. MAX6680/MAX6681 Functional Diagram

## **Detailed Description**

The MAX6680/MAX6681 are temperature sensors designed to work in conjunction with a microprocessor or other intelligence in thermostatic, process-control, or monitoring applications. Communication with the MAX6680/MAX6681 occurs through the SMBus serial interface and dedicated alert pin. The overtemperature alarm OVERT is asserted if the software or hardware programmed temperature thresholds are exceeded. OVERT can be connected to a fan, system shutdown, or other thermal management circuitry.

The MAX6680/MAX6681 convert temperatures at a programmed rate or a single conversion. Legacy mode conversions have a 1°C resolution. Legacy resolution represents temperature as 7 bits + sign bit and allows for faster autonomous conversion rates at 8Hz. The remote diode temperature can also be represented in extended-resolution mode. Extended resolution repre-

sents temperature as 10 bits + sign bit and is available for autonomous conversions that are 4Hz or slower and single-shot conversions.

The MAX6680/MAX66681 default low-temperature measurement limit is 0 °C. The device temperature measurement can be placed in extended temperature range by setting bit 3 of the Configuration register to 1. In extended temperature range, the remote and local temperature measurement range is extended down to -64°C.

### **ADC** and Multiplexer

The averaging ADC integrates over a 60ms period (each channel, typically, in the 7-bit + sign "legacy" mode). Using an averaging ADC attains excellent noise rejection.

The multiplexer automatically steers bias currents through the remote and local diodes. The ADC and associated circuitry measure each diode's forward volt-

age and computes the temperature based on this voltage. If the remote channel is not used, connect DXP to DXN. **Do not leave DXP and DXN unconnected.** When a conversion is initiated, both channels are converted whether or not they are used. The DXN input is biased at one VBE above ground by an internal diode to set up the ADC inputs for a differential measurement. Resistance in series with the remote diode causes about 1/2°C error per ohm.

#### **A/D Conversion Sequence**

A conversion sequence consists of a local temperature measurement and a remote temperature measurement. Each time a conversion begins, whether initiated automatically in the free-running autoconvert mode (RUN/STOP = 0) or by writing a One-Shot command, both channels are converted, and the results of both measurements are available after the end of conversion. A BUSY status bit in the Status register shows that the device is actually performing a new conversion. The results of the previous conversion sequence are still available when the ADC is busy.

#### **Remote-Diode Selection**

The MAX6680/MAX6681 can directly measure the die temperature of CPUs and other ICs that have on-board temperature-sensing diodes (see the *Typical Operating Circuit*) or they can measure the temperature of a discrete diode-connected transistor. The type of remote diode used is set by bit 5 of the Configuration Byte. If bit 5 is set to zero, the remote sensor is a diode-connected transistor, and if bit 5 is set to 1, the remote sensor is a substrate or common-collector PNP transistor. For best accuracy, the discrete transistor should be a small-signal device with its collector and base connected together. Accuracy has been experimentally verified for all of the devices listed in Table 1.

The transistor must be a small-signal type with a relatively high forward voltage; otherwise, the A/D input voltage range can be violated. The forward voltage at the highest expected temperature must be greater than 0.25V at 10µA, and at the lowest expected temperature, forward voltage must be less than 0.95V at 100µA. Large power transistors must not be used. Also, ensure that the base resistance is less than 100 $\Omega$ . Tight specifications for forward-current gain (50 < ß < 150, for example) indicate that the manufacturer has good process controls and that the devices have consistent VBE characteristics.

### **Thermal Mass and Self-Heating**

When sensing local temperature, these temperature sensors are intended to measure the temperature of the PC board to which they are soldered. The leads pro-

Table 1. Remote-Sensor Transistor Manufacturers

MANUFACTURER	MODEL NO.
Central Semiconductor (USA)	CMPT3904
On Semiconductor (USA)	2N3904, 2N3906
Rohm Semiconductor (USA)	SST3904
Samsung (Korea)	KST3904-TF
Siemens (Germany)	SMBT3904
Zetex (England)	FMMT3904CT-ND

**Note:** Transistors must be diode connected (base shorted to collector).

vide a good thermal path between the PC board traces and the die. Thermal conductivity between the die and the ambient air is poor by comparison, making air-temperature measurements impractical. Because the thermal mass of the PC board is far greater than that of the MAX6680/MAX6681, the device follows temperature changes on the PC board with little or no perceivable delay

When measuring the temperature of a CPU or other IC with an on-chip sense junction, thermal mass has virtually no effect; the measured temperature of the junction tracks the actual temperature within a conversion cycle. When measuring temperature with discrete remote sensors, smaller packages (e.g., a SOT23) yield the best thermal response times. Take care to account for thermal gradients between the heat source and the sensor, and ensure that stray air currents across the sensor package do not interfere with measurement accuracy.

Self-heating does not significantly affect measurement accuracy. Remote-sensor self-heating due to the diode current source is negligible. For the local diode, the worst-case error occurs when autoconverting at the fastest rate and simultaneously sinking maximum current at the  $\overline{\text{ALERT}}$  output. For example, with V<sub>CC</sub> = 5.0V, an 8Hz conversion rate, and  $\overline{\text{ALERT}}$  sinking 1mA, the typical power dissipation is V<sub>CC</sub> × 550µA + 0.4V × 1mA, which equals 2.75mW;  $\theta_{\text{J-A}}$  for the 16-pin QSOP package is about +120°C/W, so assuming no copper PC board heat sinking, the resulting temperature rise is:

 $\Delta T = 2.75 \text{mW} \times 120 ^{\circ}\text{C} / \text{W} = 0.330 ^{\circ}\text{C}$ 

Even under these engineered circumstances, it is difficult to introduce significant self-heating errors.

#### **ADC Noise Filtering**

The integrating ADC used has good noise rejection for low-frequency signals such as 60Hz/120Hz power-sup-

ply hum. In noisy environments, high-frequency noise reduction is needed for high-accuracy remote measurements. The noise can be reduced with careful PC board layout and proper external noise filtering.

High-frequency EMI is best filtered at DXP and DXN with an external 2200pF capacitor. Larger capacitor values can be used for added filtering, but do not exceed 3300pF because it can introduce errors due to the rise time of the switched current source.

#### **PC Board Layout**

Follow these guidelines to reduce the measurement error of the temperature sensors:

- Place the MAX6680/MAX6681 as close as is practical to the remote diode. In noisy environments, such as a computer motherboard, this distance can be 4in to 8in (typ). This length can be increased if the worst noise sources are avoided. Noise sources include CRTs, clock generators, memory buses, and ISA/PCI buses.
- 2) Do not route the DXP-DXN lines next to the deflection coils of a CRT. Also, do not route the traces across fast digital signals, which can easily introduce 30°C error, even with good filtering.
- 3) Route the DXP and DXN traces in parallel and in close proximity to each other, away from any higher voltage traces, such as 12VDC. Leakage currents from PC board contamination must be dealt with carefully since a  $20M\Omega$  leakage path from DXP to ground causes about 1°C error. If high-voltage traces are unavoidable, connect guard traces to GND on either side of the DXP-DXN traces (Figure 2).
- Route through as few vias and crossunders as possible to minimize copper/solder thermocouple effects.
- 5) When introducing a thermocouple, make sure that both the DXP and the DXN paths have matching thermocouples. A copper-solder thermocouple exhibits 3μV/°C, and it takes about 200μV of voltage error at DXP-DXN to cause a 1°C measurement error. Adding a few thermocouples causes a negligible error.
- 6) Use wide traces. Narrow traces are more inductive and tend to pick up radiated noise. The 10mil widths and spacings that are recommended in Figure 2 are not absolutely necessary, as they offer only a minor improvement in leakage and noise over narrow traces. Use wider traces when practical.
- 7) Add a  $200\Omega$  resistor in series with V<sub>CC</sub> for best noise filtering (see the *Typical Operating Circuit*).

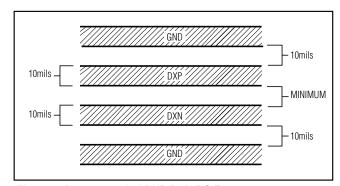


Figure 2. Recommended DXP-DXN PC Traces

#### **Twisted-Pair and Shielded Cables**

Use a twisted-pair cable to connect the remote sensor for remote-sensor distances longer than 8in or in very noisy environments. Twisted-pair cable lengths can be between 6ft and 12ft before noise introduces excessive errors. For longer distances, the best solution is a shielded twisted pair like that used for audio microphones. For example, Belden 8451 works well for distances up to 100ft in a noisy environment. At the device, connect the twisted pair to DXP and DXN and the shield to GND. Leave the shield unconnected at the remote sensor.

For very long cable runs, the cable's parasitic capacitance often provides noise filtering, so the 2200pF capacitor can often be removed or reduced in value. Cable resistance also affects remote-sensor accuracy. For every  $1\Omega$  of series resistance, the error is approximately  $1/2^{\circ}\text{C}$  error.

### **Low-Power Standby Mode**

Standby mode reduces the supply current to less than 10µA by disabling the ADC. Enter hardware standby by forcing the STBY pin low, or enter software standby by setting the RUN/STOP bit to 1 in the Configuration Byte register. Hardware and software standbys are very similar: all data is retained in memory, and the SMB interface is alive and listening for SMBus commands, but the SMBus timeout is disabled. The only difference is that in software standby mode, the One-Shot command initiates a conversion. With hardware standby, the One-Shot command is ignored. Activity on the SMBus causes the device to draw extra supply current (see the *Typical Operating Characteristics*).

Driving the STBY pin low overrides any software conversion command. If a hardware or software standby command is received while a conversion is in progress, the conversion cycle is interrupted, and the tempera-

Vrite E	Byte Form	at														
S	ADD	RESS	,	WR	ACI	<b>&lt;</b>	CON	IMANE	)	ACK	1	DATA		ACK		Р
	7	bits					8	bits				8 bits				1
Read B	Slave Address: equiva- lent to chip-select line of a 3-wire interface  Command Byte: selects which register you are writing to a 3-wire interface					set k	y th holds	e com s, confi	goes into t nmand by guration m	te (to s	et					
	ADDRESS	s w	R A	CK	COMMA	AND	ACK	s	ΑI	DDRESS	RD	Α	СК	DATA	///	Р
	7 bits				8 bits	S				7 bits				8 bits		
end B	Slave Add lent to chip	-select		-	Commanwhich re reading for	gister		9	due flow	ve Address to chang direction	e in d	ata-		Data Byte: the registe command	er set by	
	ADDRESS	WR	ACK	СО	MMAND	ACK	Р		S	ADDRE		RD	ACK	DATA	///	Р
	7 bits			8	3 bits					7 bits				8 bits		
	t condition		eded = S : Not ac	mand used Slave	mand Byte d with no for one-si	data, hot cor	usually				·			Data Byte: the regist by the las Write Byte also used Response	er comr st Read e transr for SME	nande Byte nissic us Al

Figure 3. SMBus Protocols

ture registers are not updated. The previous data is not changed and remains available.

#### SMBus Digital Interface

From a software perspective, the MAX6680/MAX6681 appear as a series of 8-bit registers that contain temperature data, alarm threshold values, and control bits. A standard SMBus-compatible 2-wire serial interface is used to read temperature data and write control bits and alarm threshold data. The device responds to the same SMBus slave address for access to all functions.

The MAX6680/MAX6681 employ four standard SMBus protocols: Write Byte, Read Byte, Send Byte, and Receive Byte (Figure 3). The shorter Receive Byte protocol allows quicker transfers, provided that the correct data register was previously selected by a Read Byte instruction. Use caution with the shorter protocols in multimaster systems, since a second master could overwrite the command byte without informing the first master.

When the conversion rate is 8Hz, temperature data can be read from the Read Internal Temperature (00h) and Read External Temperature (01h) registers. The temperature data format in these registers is 7 bits + sign in two's-complement form for each channel, with the LSB representing 1°C (Table 2). The MSB is transmitted first. Extended range extends the temperature data range of the local and remote sensor to -64°C. Extended range is activated by setting bit 3 of the Configuration register to 1.

When the conversion rate is 4Hz or less, temperature data can be read from the Read Internal Temperature (00h) and Read External Temperature (01h) registers, the same as for faster conversion rates. An additional 3 bits can be read from the Read External Extended Temperature (10h), which extends the remote temperature data to 10 bits + sign and the resolution to 0.125°C per LSB (Table 3).

When a conversion is complete, the Main register and the Extended register are updated almost simultaneously. Ensure that no conversions are completed between reading the Main and Extended registers so that when data that is read by both registers contain the result of the same conversion.

To ensure valid extended data, read extended resolution temperature data using one of the following approaches:

- Put the MAX6680/MAX6681 into standby mode by setting bit 6 of the Configuration register to 1. Initiate a one-shot conversion using Send Byte command 0Fh. When this conversion is complete, read the contents of the temperature data registers.
- 2) If the MAX6680/MAX6681 are in run mode, read the Status register. If a conversion is in progress, the BUSY bit is set to 1. Wait for the conversion to complete as indicated by the BUSY bit being set to zero, then read the temperature data registers.

#### **Diode Fault Alarm**

There is a continuity fault detector at DXP that detects an open circuit between DXP and DXN, or a DXP short to V<sub>CC</sub>, GND, or DXN. If an open or short circuit exists, the External Temperature register is loaded with 1000 0000. Additionally, if the fault is an open circuit, bit 2 (OPEN) of the Status byte is set to 1 and the ALERT condition is activated at the end of the conversion. Immediately after power-on reset, the Status register indicates that no fault is present until the end of the first conversion.

#### **Alarm Threshold Registers**

Four registers store ALERT threshold values—one high-temperature (T<sub>HIGH</sub>) and one low-temperature (T<sub>LOW</sub>) register each for the local and remote channels. If either measured temperature equals or exceeds the corresponding ALERT threshold value, the ALERT output is asserted.

The POR state of both ALERT THIGH registers is 0111 1111 or +127°C and the POR state of TLOW registers is 1100 1001 or -55°C.

Two additional registers, RWOE and RWOI, store remote and local alarm threshold data information corresponding to the OVERT output (see the OVERT Overtemperature Alarm section).

#### ALERT

The ALERT output operates in two modes—the typical interrupt mode and comparator mode. The INT\_SEL input determines the mode. When INT\_SEL is connected to VCC high, using a weak pullup resistor, or left floating, the ALERT functions in the interrupt mode.

#### **ALERT** Interrupt Mode

An ALERT interrupt occurs when the internal or external temperature reading exceeds a high or low temperature limit (user programmed) or when the remote diode is disconnected (for continuity fault detection). The

ALERT interrupt output signal is latched and can be cleared only by either reading the Status register or by successfully responding to an Alert Response address. In both cases, the alert is cleared even if the fault condition still exists, but is reasserted at the end of the next conversion. The interrupt does not halt automatic conversions. The interrupt output pin is open drain so that multiple devices can share a common interrupt line. The interrupt rate never exceeds the conversion rate.

#### Comparator Mode

Connecting INT\_SEL to ground operates the ALERT output in comparator mode. In the comparator mode, whenever the temperature of the remote or local temp sensor goes outside the limits set by THIGH or TLOW, the ALERT output becomes inactive after the tempera-

**Table 2. Data Format (Two's Complement)** 

TEMP (°C)	LEGACY MODE DIGITAL OUTPUT	EXTENDED RANGE DIGITAL OUTPUT
127.00	0111 1111	0111 1111
25	0001 1001	0001 1001
1	0000 0001	0000 0001
0.00	0000 0000	0000 0000
-1	0000 0000	1111 1111
-25	0000 0000	1110 0111
-64	0000 0000	1000 0000
Diode Fault (Short or Open)	1000 0000	1000 0000

**Table 3. Extended Resolution Register** 

FRACTIONAL TEMPERATURE	CONTENTS OF EXTENDED REGISTER
0.000	000X XXXX
0.125	001X XXXX
0.250	010X XXXX
0.375	011X XXXX
0.500	100X XXXX
0.625	101X XXXX
0.750	110X XXXX
0.875	111X XXXX

**Note:** Extended mode applies only for conversion rates of 4Hz and slower

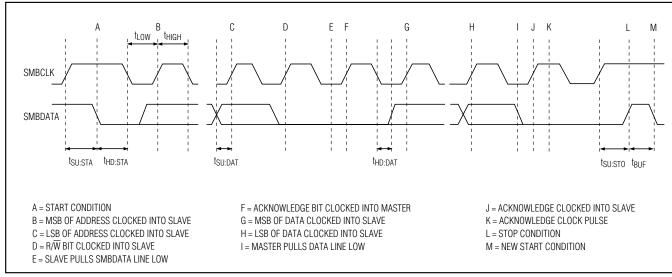


Figure 4. SMBus Write Timing Diagram

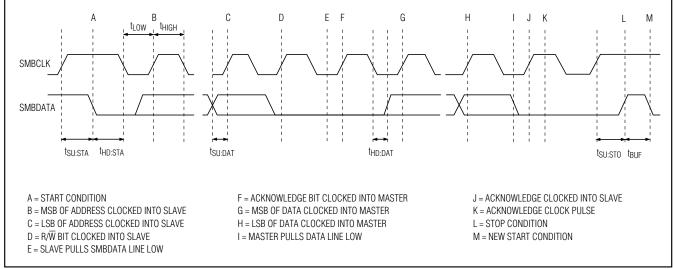


Figure 5. SMBus Read Timing Diagram

ture returns within the limits. An open diode also sets this output.

#### **Alert Response Address**

The SMBus Alert Response interrupt pointer provides quick fault identification for simple slave devices that lack the complex, expensive logic needed to be a bus master. Upon receiving an ALERT interrupt signal, the host master can broadcast a Receive Byte transmission to the Alert Response slave address (see the *Slave* 

Addresses section). Then, any slave device that generated an interrupt, attempts to identify itself by putting its own address on the bus (Table 4).

The Alert Response can activate several different slave devices simultaneously, similar to the I<sup>2</sup>C General Call. If more than one slave attempts to respond, bus arbitration rules apply, and the device with the lower address code wins. The losing device does not generate an acknowledge and continues to hold the ALERT line low until cleared. (The conditions for clearing an alert vary

depending on the type of slave device.) Successful completion of the Alert Response protocol clears the interrupt latch, provided the condition that caused the alert no longer exists. If the condition still exists, the device reasserts the ALERT interrupt at the end of the next conversion.

#### **OVERT** Overtemperature Alarm

Two registers, RWOE and RWOI, store remote and local alarm threshold data corresponding to the OVERT output. The values stored in these registers are high-temperature thresholds. If any one of the measured temperatures equals or exceeds the corresponding alarm threshold value, an OVERT output is asserted.

The overtemperature thresholds are both hardware and software programmable. The overtemperature thresholds can be hardware programmed by pin strapping CRITO and CRIT1. Use Table 4 to set the desired remote and local threshold temperatures. Upon POR or driving the RESET pin high, the Overtemperature register takes on the hardware-programmed values. Afterward, any write to the Overtemperature registers overwrites the hardware-programmable values.

OVERT always operates in comparator mode and is asserted when the temperature rises to a value programmed in the appropriate threshold register. It is deasserted when the temperature drops below this threshold minus the programmed value in the Hysteresis (HYST) register. An OVERT output can be used to activate a cooling fan, send a warning, initiate clock throttling, or trigger a system shutdown to prevent component damage. The HYST byte sets the amount of hysteresis to deassert the OVERT output. The data format for the HYST byte is 7 bits + sign with 1°C resolution. Bit 7 of the HYST register should always be zero.

#### **Command Byte Functions**

The 8-bit Command Byte register (Table 5) is the master index that points to the various other registers within the MAX6680/MAX6681. This register's POR state is 0000 0000, so a Receive Byte transmission (a protocol that lacks the command byte) occurring immediately after POR returns the current local temperature data.

### One Shot

The One-Shot command immediately forces a new conversion cycle to begin. If the One-Shot command is received when the MAX6680/MAX6681 is in software standby mode (RUN/STOP bit = 1), a new conversion is begun, after which the device returns to standby mode. If a conversion is in progress when a One-Shot command is received, the command is ignored. If a One-Shot command is received in autoconvert mode (RUN/STOP)

Table 4. OVERT Temperature Threshold Programming

CRIT1	CRIT0	OVERT THRESHOLD (°C)				
CRITI	Chilu	REMOTE	LOCAL			
GND	GND	+85	+70			
GND	Open	+90	+75			
GND	Vcc	+95	+80			
Open	GND	+100	+85			
Open	Open	+105	+90			
Open	Vcc	+110	+95			
Vcc	GND	+115	+100			
Vcc	Open	+120	+105			
Vcc	Vcc	+125	+110			

bit = 0) between conversions, a new conversion begins, the conversion rate timer is reset, and the next automatic conversion takes place after a full delay elapses.

#### **Configuration Byte Functions**

The Configuration Byte register, Table 6, is a read-write register with several functions. Bit 7 is used to mask (disable) ALERT interrupts. Bit 6 puts the device into software standby mode (STOP) or autonomous (RUN) mode. Bit 5 selects the type of external junction (set to 0 for a substrate PNP on an IC or set to 1 for a discrete diode-connected transistor) for optimized measurements. Bit 4 selects the extended temperature measurement for the remote sensor. If high, the temperature data is available as 10 bits + sign with a 0.125°C resolution, otherwise, 7 bits + sign with 1°C resolution. Bit 4 extends the temperature range of the remote and local temperature sensor to -64°C. Bit 2 disables the SMBus timeout, as well as the Alert Response. Bit 1 provides a software reset from the SMBus. Bit 0 is reserved and returns a zero when read.

#### Status Byte Functions

The status byte (Table 7) indicates which (if any) temperature thresholds have been exceeded. This byte also indicates whether the ADC is converting and if there is an open-circuit fault detected with the external sense junction. After POR, the normal state of the registers' bits is zero, assuming no alert or overtemperature conditions are present. When operating the MAX6680/MAX6681 in ALERT interrupt mode, bits 2 through 6 of the Status register are cleared by any successful read of the Status register, unless the fault persists. The ALERT output follows the status flag bit. Both are cleared when successfully read, but if the condition

Table 5. Command-Byte Register Bit Assignments

REGISTER	ADDRESS	POR STATE	FUNCTION
RLTS	00h	0000 at 0°C	Read Internal Temperature
RRTE	01h	0000 (0°C)	Read External Temperature
RSL	02h	0000 0000	Read Status Register
RCL/WCL	03h/09h	0010 0000	Read/Write Configuration Byte
RCRA/WCRA	04h/0A	0000 0010	Read/Write Conversion Rate Byte
RIH/WIH	05h/0Bh	0111 1111 (+127°C)	Read/Write Internal ALERT High Limit
RIL/WIL	06h/0Ch	1100 1001 ( -55°C)	Read/Write Internal ALERT Low Limit
REH/WEH	07h/0Dh	0100 0110 (+127°C)	Read/Write External ALERT High Limit
REL/WEL	08h/0Eh	1100 1001 (-55°C)	Read/Write External ALERT Low Limit
OSHT	0Fh	0000	One Shot
REET	10h	0000 0000	Read External Extended Temperature
RWOH	11h	0000 0000	Read/Write External Offset High Byte
RWOL	12h	0000 0000	Read/Write External Offset Low Byte
RWOE	19h	See Table 4	Read/Write External OVERT Limit
RWOI	20h	See Table 4	Read/Write Internal OVERT Limit
HYST	21h	0000 0110 (+6°C)	OVERT Hysteresis
RDID	FEh	0100 1101	Read Manufacturer ID
RDRV	Ff	0000 0001	Read Device Revision

still exists, they are reasserted at the end of the next conversion. If the MAX6680/MAX6681 are operating in the comparator mode, bits 2–6 of the Status register are cleared only after the local and/or remote temperatures return within the set limits.

The bits indicating OVTI and OVTE are cleared only when the condition no longer exists. Reading the status byte does not clear the OVERT output or fault bits. One way to eliminate the fault condition is for the measured temperature to drop below the temperature threshold minus the hysteresis value. Another way to eliminate the fault condition is by writing new values for the RWOI, RWOE, or HYST registers so that a fault condition is no longer present.

The MAX6680/MAX6681 incorporate collision avoidance so that completely asynchronous operation is allowed between SMBus operations and temperature conversions.

When autoconverting, if the T<sub>HIGH</sub> and T<sub>LOW</sub> limits are close together, it is possible for both high-temp and low-temp status bits to be set, depending on the amount of time between status read operations. In these circumstances, it is best not to rely on the status bits to indicate reversals in long-term temperature changes. Instead use a current temperature reading to establish the trend direction.

### **Hardware/Software Reset**

The MAX6680/MAX6681 reset at power-on if pin 7 is taken high, or by software reset through bit 1 of the Configuration register. When reset occurs, all registers go to default values, and the SMBus address pins are sampled.

#### **Conversion Rate Byte**

The Conversion Rate register (Table 8) programs the time interval between conversions in free-running

Table 6. Configuration-Byte Bit Assignment

BIT	NAME	POR STATE	FUNCTION	
7 (MSB)	ALERT MASK	0	Mask ALERT active state when 1. When 1, ALERT does not respond to any fault related to the four limit registers.	
6	RUN/STOP	0	Standby mode control bit; if 1, immediately stops converting and enters standby mode. If zero, it converts in either one-shot or timer mode.	
5	SPNP	1	When 1, the remote sensor is a common-collector substrate PNP. When zero, the remote sensor is a diode-connected transistor.	
4	Extended Resolution	0	When zero, remote- and local-sensors' temperature data are 7 bits + sign with 1°C resolution. When 1, the remote-sensor temperature data is 10 bits + sign with 0.125°C resolution.	
3	Extended Range	0	Extended temperature range. 0 = normal, 1 = extended to -64°C.	
2	SMBus Timeout	0	When set to 1, it disables the SMBus timeout, as well as the alert response.	
1	Software Reset	0	Software reset from SMBus from customer.	
0	RFU	0	Reserved	

**Table 7. Status Register Bit Assignments** 

BIT	NAME	POR STATE	FUNCTION
7 (MSB)	BUSY	0	When 1, the A/D is busy converting.
6	LHIGH	0	When 1, internal high-temperature alarm has tripped; cleared by POR or readout of the Status register, if the fault condition no longer exists.
5	LLOW	0	When 1, internal low-temperature alarm has tripped; cleared by POR or readout of the Status register, if the fault condition no longer exists.
4	RHIGH	0	When 1, external high-temperature alarm has tripped; cleared by POR or readout of the Status register, if the fault condition no longer exists.
3	RLOW	0	When 1, external low-temperature alarm has tripped; cleared by POR or readout of the Status register if the fault condition no longer exists.
2	OPEN	0	When 1 indicates an external diode open; cleared by POR or readout of the Status register, if the fault condition no longer exists.
1	OVI	0	When 1, internal temperature exceeds the RWOI limit.
0	OVE	0	When 1, external temperature exceeds the RWOE limit.

autonomous mode (RUN/STOP = 0). This variable rate control can be used to reduce the supply current in portable-equipment applications. The conversion rate byte's POR state is 02h (0.25Hz). The MAX6680/MAX6681 use only the 3LSBs of this register. The 5MSBs are "don't care" and should be set to zero when possible. The conversion rate tolerance is  $\pm 25\%$  at any rate setting.

Valid A/D conversion results for both channels are available one total conversion time (125ms nominal, 156ms maximum) after initiating a conversion, whether conversion is initiated through the RUN/STOP bit, hardware STBY pin, One-Shot command, or initial power-up.

#### **Slave Addresses**

The MAX6680/MAX6681 device address can be initially set to nine different values by pin strapping ADD0 and ADD1 so that more than one MAX6680/MAX6681 can

reside on the same bus without address conflicts (Table 9).

The address pin states are checked at POR and RESET only, and the address data stays latched to reduce quiescent supply current due to the bias current needed for high-Z state detection. The MAX6680/MAX6681 also respond to the SMBus Alert Response slave address (see the *Alert Response Address* section).

#### **POR and UVLO**

The MAX6680/MAX6681 have a volatile memory. To prevent unreliable power-supply conditions from corrupting the data in memory and causing erratic behavior, a POR voltage detector monitors V<sub>CC</sub> and clears the memory if V<sub>CC</sub> falls below 1.91V (typ, see *Electrical Characteristics*). When power is first applied and V<sub>CC</sub> rises above 2.0V (typ), the logic blocks begin operating, although reads and writes at V<sub>CC</sub> levels below 3.0V are not recommended. A second V<sub>CC</sub> comparator, the ADC UVLO comparator, prevents the ADC from converting until there is sufficient headroom (V<sub>CC</sub> = 2.8V typ).

#### Power-Up Defaults

- Interrupt latch is cleared.
- Address select pin is sampled.
- ADC begins autoconverting at a 1Hz rate (legacy resolution).
- Command register is set to 00h to facilitate quick internal Receive Byte queries.
- T<sub>HIGH</sub> and T<sub>LOW</sub> registers are set to max and min limits, respectively.
- Hysteresis is set to 6°C.
- Transistor type is set to a substrate or common-collector PNP.

#### **Temperature Offset**

The MAX6680/MAX6681 are designed to provide  $\pm 1^{\circ}$ C accuracy for common microprocessors and discrete transistors. To accommodate processes that differ significantly in their ideality factor, the user can increase/decrease the Remote Temperature Sensor Data register with an offset by writing to the External Offset High and Low Byte registers (11h and 12h, respectively). The offset temperature data is represented as a 10 bits + sign with a 0.125LSB resolution.

**Table 8. Conversion-Rate Control Byte** 

DATA	CONVERSION RATE (Hz)
00h	0.0625
01h	0.125
02h	0.25
03h	0.5
04h	1
05h	2
06h	4
07h	8

**Note:** If extended resolution is selected using bit 4 of the Configuration register, the extended conversion is limited to a maximum of 4Hz.

# Table 9. POR Slave Address Decoding (ADD0 and ADD1)

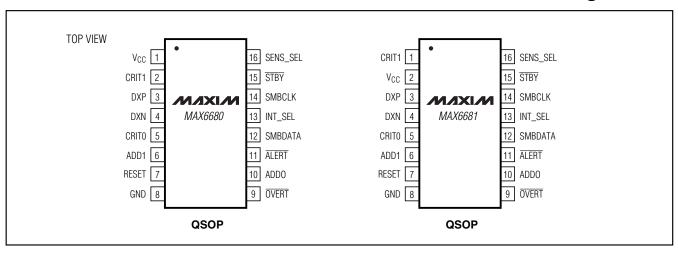
ADD0	ADD1	ADDRESS
GND	GND	0011 000
GND	HIGH-Z	0011 001
GND	V <sub>C</sub> C	0011 010
HIGH-Z	GND	0101 001
HIGH-Z	HIGH-Z	0101 010
HIGH-Z	VCC	0101 011
Vcc	GND	1001 100
Vcc	HIGH-Z	1001 101
Vcc	V <sub>CC</sub>	1001 110

Chip Information

TRANSISTOR COUNT: 17,150

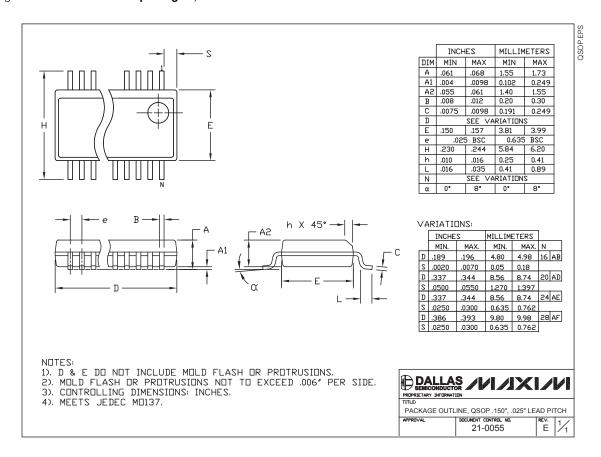
PROCESS: BICMOS

## Pin Configurations



## Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



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